



DPLS350E

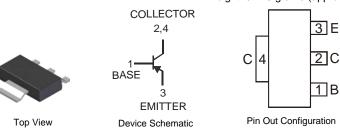
LOW V<sub>CE(SAT)</sub> PNP SURFACE MOUNT TRANSISTOR

#### Features

- Epitaxial Planar Die Construction
- Ideally Suited for Automated Assembly Processes
- Ideal for Medium Power Switching or Amplification Applications
- Lead Free By Design/RoHS Compliant (Note 1)
- "Green" Device (Note 2)

#### **Mechanical Data**

- Case: SOT-223
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Finish Matte Tin annealed over Copper leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.115 grams (approximate)



#### **Maximum Ratings** $@T_A = 25^{\circ}C$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-60	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-50	V
Emitter-Base Voltage	V <sub>EBO</sub>	-6	V
Peak Pulse Current	I <sub>CM</sub>	-5	A
Continuous Collector Current	I <sub>C</sub>	-3	A
Base Current	IB	-1	А

### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 3) @ T <sub>A</sub> = 25°C	PD	1	W
Thermal Resistance, Junction to Ambient Air (Note 3) @ T <sub>A</sub> = 25°C	$R_{ ext{ heta}JA}$	125	°C/W
Operating and Storage Temperature Range	TJ, T <sub>STG</sub>	-55 to +150	°C

Notes: 1. No purposefully added lead.

2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead\_free/index.php.

 Device mounted on FR-4 PCB; pad layout as shown on page 4 or in Diodes Icc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.



# **Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
OFF CHARACTERISTICS (Note 4)						
Collector-Base Cutoff Current		_	_	-100	nA	$V_{CB} = -50V, I_E = 0$
	ГСВО		_	-50	μA	V <sub>CB</sub> = -50V, I <sub>E</sub> = 0, T <sub>A</sub> = 150°C
Emitter-Base Cutoff Current	I <sub>EBO</sub>	_	_	-100	nA	$V_{EB} = -5V, I_{C} = 0$
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	-50	_	_	V	I <sub>C</sub> = -100μA
Collector-Emitter Breakdown Voltage	V <sub>(BR)CEO</sub>	-50	_	_	V	I <sub>C</sub> = -10mA
Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	-5	_	_	V	I <sub>E</sub> = -100μA
ON CHARACTERISTICS (Note 4)						• •
DC Current Gain		200		—		$V_{CE} = -2V, I_{C} = -0.5A$
	h <sub>FE</sub>	200		_		$V_{CE} = -2V, I_{C} = -1A$
		100	—	_		$V_{CE} = -2V, I_{C} = -2A$
Collector-Emitter Saturation Voltage		_		-100	mV	$I_{C} = -0.5A, I_{B} = -50mA$
	V <sub>CE(SAT)</sub>		—	-180		I <sub>C</sub> = -1A, I <sub>B</sub> = -50mA
		_		-300		$I_{\rm C} = -2A, I_{\rm B} = -200 {\rm mA}$
Equivalent On-Resistance	R <sub>CE(SAT)</sub>	_	67	150	mΩ	I <sub>E</sub> = -2A, I <sub>B</sub> = -200mA
Base-Emitter Saturation Voltage	V <sub>BE(SAT)</sub>	_	_	-1.2	V	I <sub>C</sub> = -2A, I <sub>B</sub> = -200mA
Base-Emitter Turn-on Voltage	V <sub>BE(ON)</sub>		_	-1.1	V	$V_{CE} = -2V, I_{C} = -1A$
SMALL SIGNAL CHARACTERISTICS	· · · · ·					
Transition Frequency	f <sub>T</sub>	100	—	—	MHz	V <sub>CE</sub> = -5V, I <sub>C</sub> = -100mA, f = 100MHz
Output Capacitance	C <sub>obo</sub>		_	40	pF	V <sub>CB</sub> = -10V, f = 1MHz

Notes: 4. Measured under pulsed conditions. Pulse width =  $300\mu$ s. Duty cycle  $\leq 2\%$ .

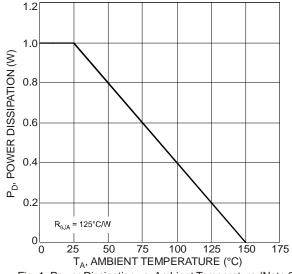
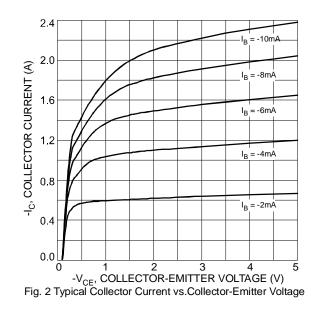
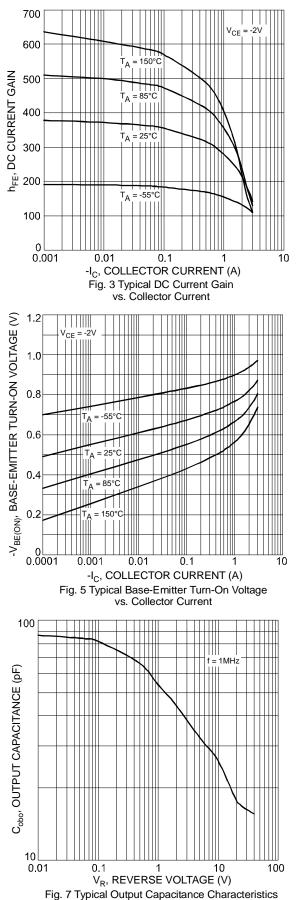


Fig. 1 Power Dissipation vs. Ambient Temperature (Note 3)







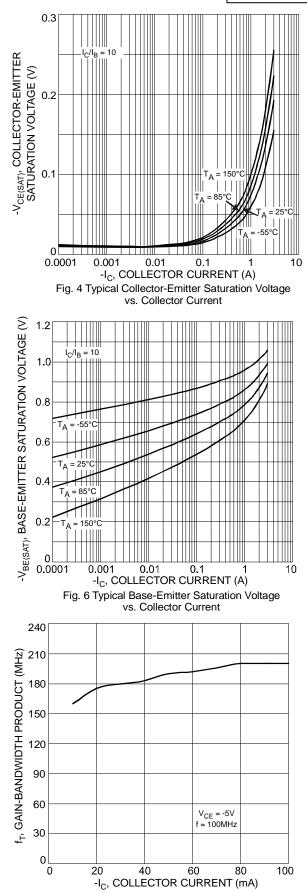


Fig. 8 Typical Gain-Bandwidth Product vs. Collector Current

DPLS350E Document number: DS31230 Rev. 4 - 2

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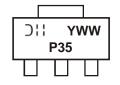


### Ordering Information (Note 5)

Part Number	Case	Packaging
DPLS350E-13	SOT-223	2500/Tape & Reel

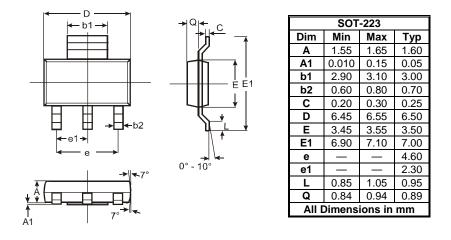
Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

### **Marking Information**

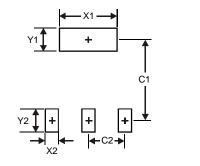


P35 = Product Type Marking Code ) | = Manufacturer's Code Marking YWW = Date Code Marking Y = Last digit of year (ex: 7 = 2007) WW = Week code 01 - 52

## **Package Outline Dimensions**



# **Suggested Pad Layout**



Dimensions	Value (in mm)
X1	3.3
X2	1.2
Y1	1.6
Y2	1.6
C1	6.4
C2	2.3



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